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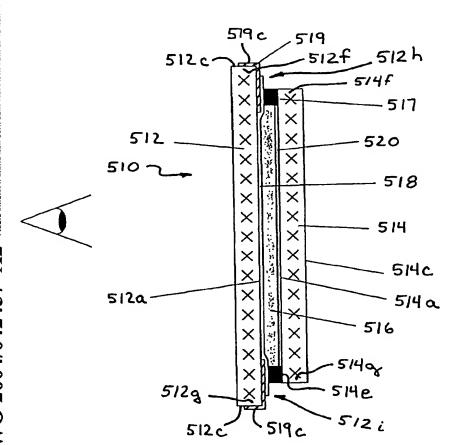
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(54) Title: ELECTRO-OPTIC REFLECTIVE ELEMENT ASSEMBLY



(57) Abstract: An electro-optic reflective element assembly (510) includes a pair of substrates (512, 514) and an electro-optic medium (516) sandwiched therebetween. Each of the pair of substrates includes at least one conductive or semi-conductive layer (518, 520) disposed thereon. The electrical connections may electrically connect to a respective layer and may be electrically isolated from the other layer, such as via non-conductive regions (514e) of the substrates and/or deletion lines along one of the conductive layers. The pair of substrates may be positioned relative to one another such that overhang portions (512h, 512i) of the front substrate (512) extend beyond the corresponding edges of the rear substrate (514). The overlapping relationship may provide clearance for electrical connection to the conductive layers of the front and rear substrates such that the electrical connections are substantially not viewable through the front substrate.

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